

PAUL SCHERRER INSTITUT

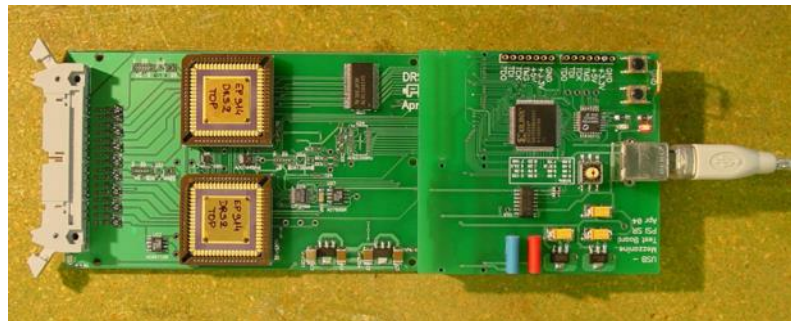


Stefan Ritt :: Head of Muon Physics Group :: Paul Scherrer Institut

Experiences with picosecond level timing in large systems

FAST2023, Elba, May 30, 2023

Scope of this talk



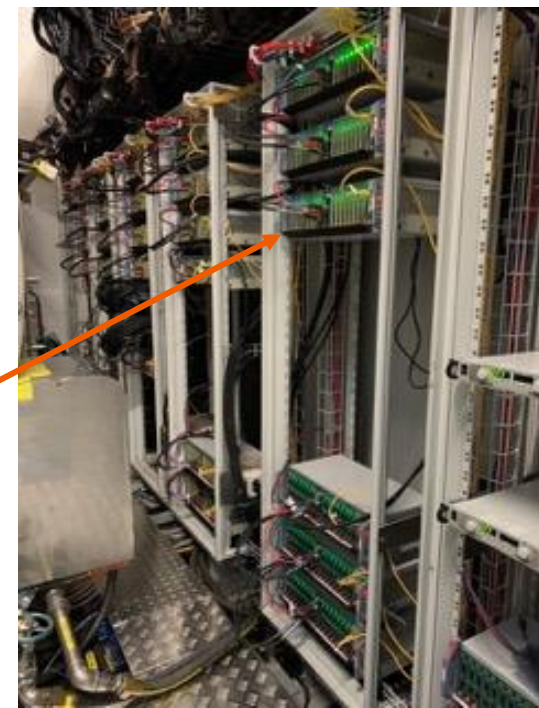
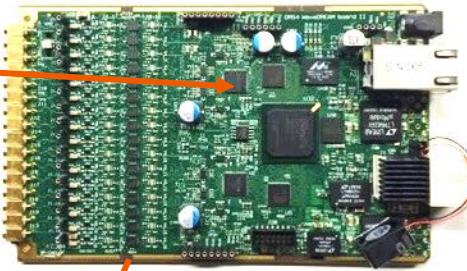
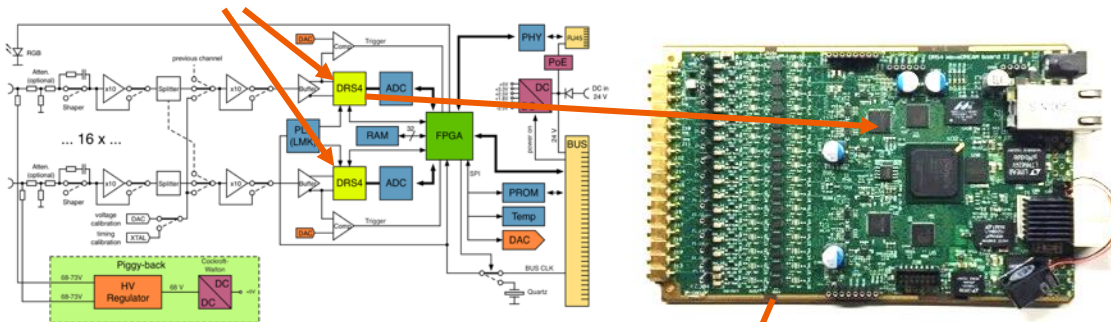
Prototype



Full system

WaveDAQ system for MEG II @ PSI

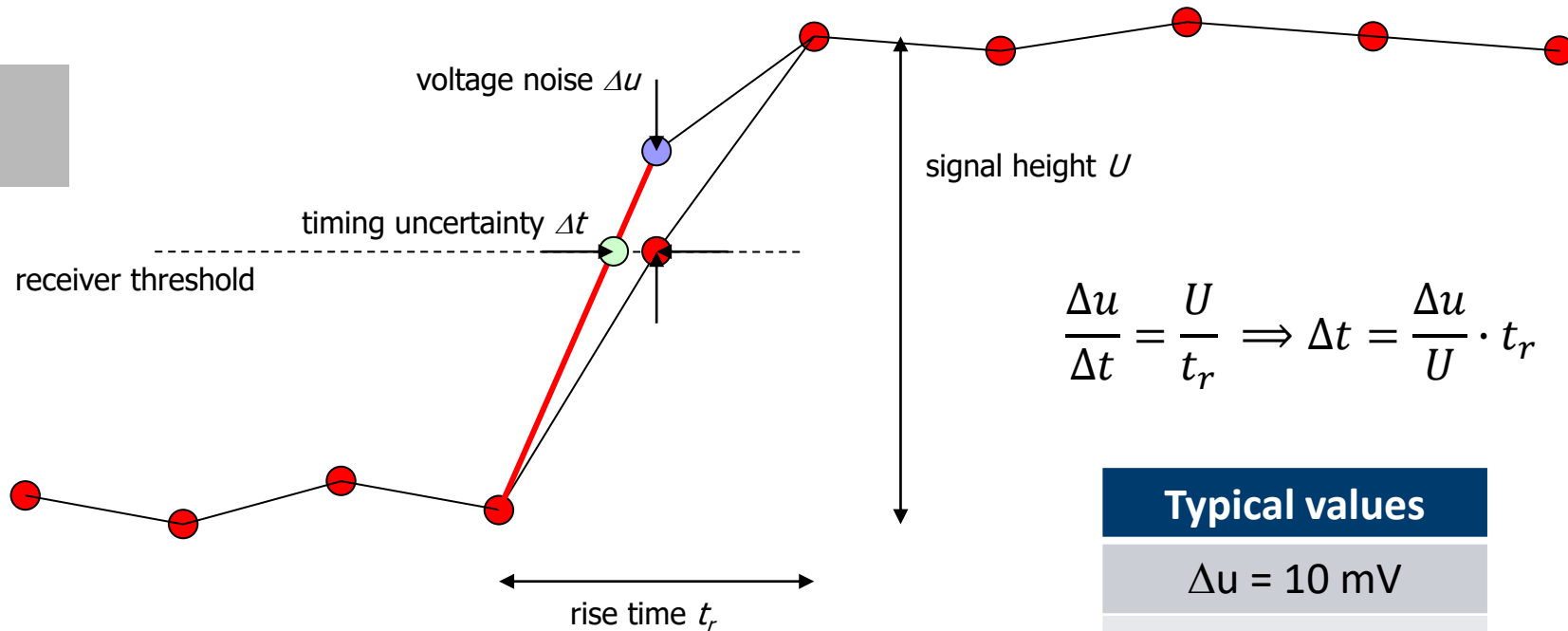
DRS4 chip



9000+ channels 5 GSPS / 12 bit

- Switched Capacitor Array chips (**SCA** recap)
- Sources of timing jitter: Single ended lines, **PLL jitter**
- **Noise reduction** strategies
- **Lessons learned** with the MEG II system (9000+ channels)

Jitter caused by voltage noise



$$\frac{\Delta u}{\Delta t} = \frac{U}{t_r} \Rightarrow \Delta t = \frac{\Delta u}{U} \cdot t_r$$

Typical values

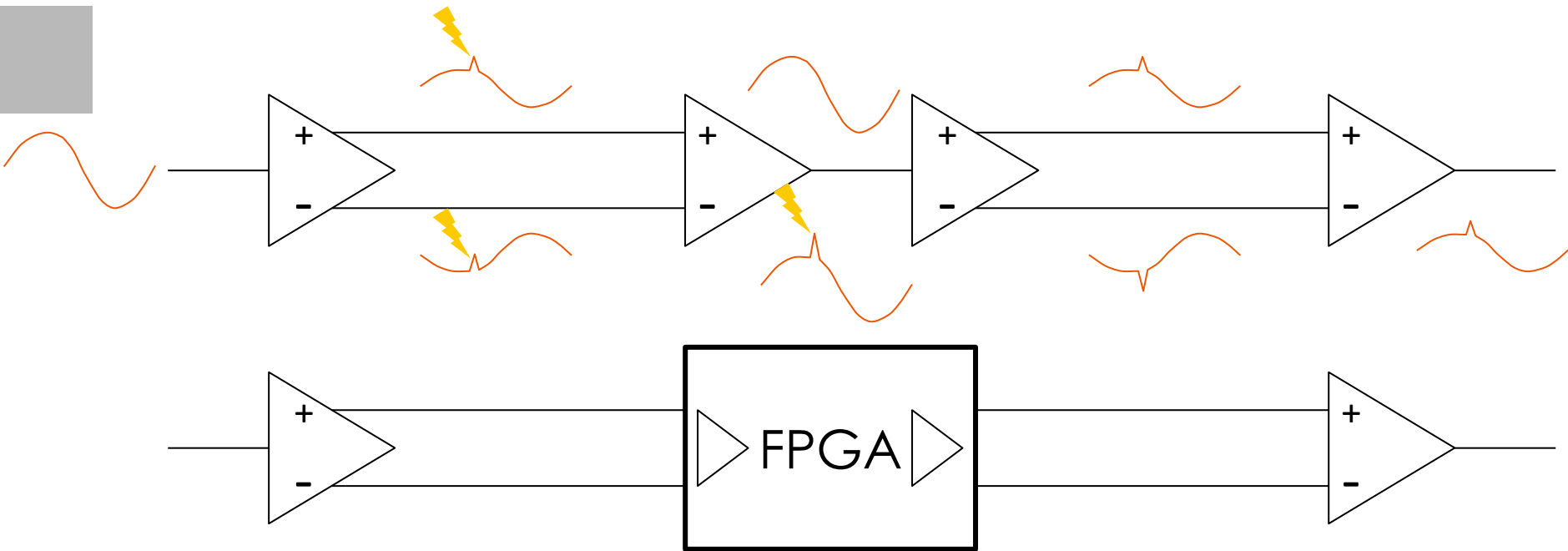
$$\Delta u = 10 \text{ mV}$$

$$U = 3.3 \text{ V}$$

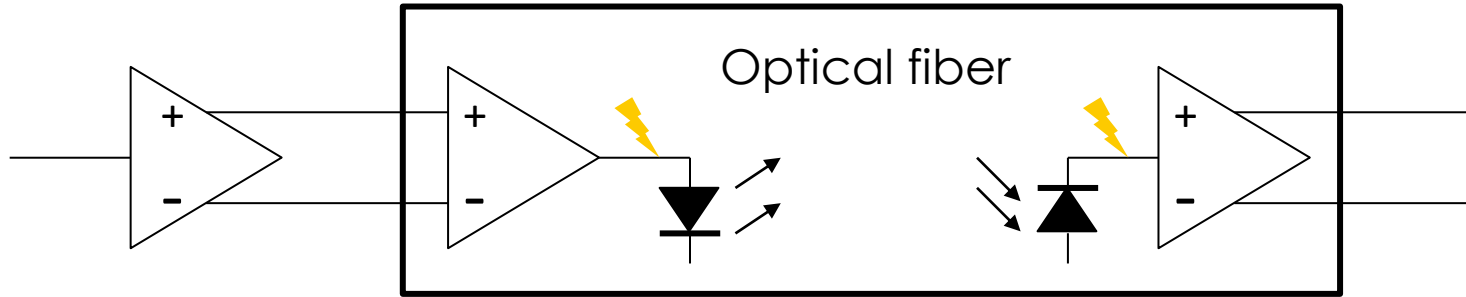
$$t_r = 1 \text{ ns}$$

$$\Delta t = 3 \text{ ps}$$

Differential Signals e.g. LVDS



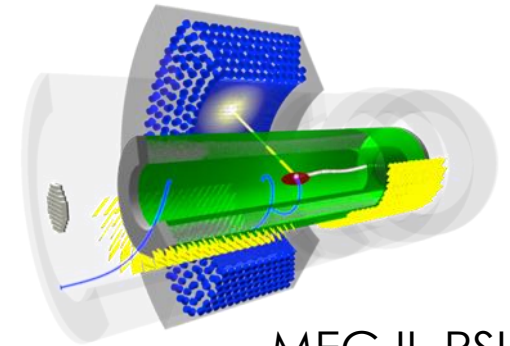
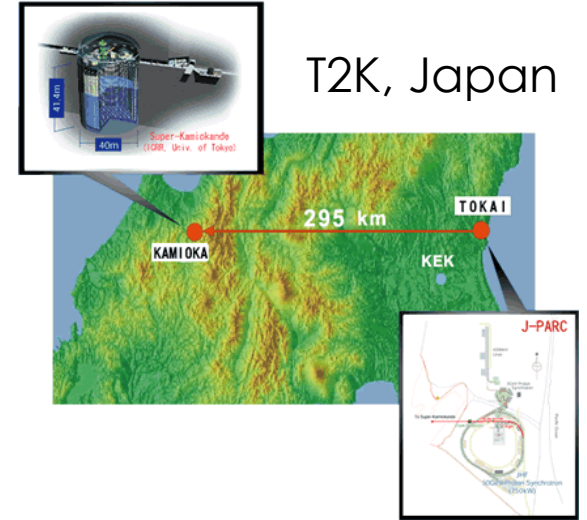
Do not send low-jitter clocks through FPGAs!



Careful with optical clock distribution!

Clock stability

- **GPS** clock for measurements **far apart**
- **Atomic** clock for **long term** measurements
- Particle physics: Measurement periods **$O(100 \text{ ns})$**
- Excellent **low-jitter** clock distribution to all detector channels



MEG II, PSI

Low-jitter quartz

MEMS CLOCK OSCILLATOR

ASEMP

Life Size
3.2 x 2.5 x 0.85 mm

Moisture Sensitivity Level – MSL 1

FEATURES:

- Low Power Consumption for high speed communication
- Exceptional Stability Over Temp. at -40 to +85°C, ±15ppm
- Extended Automotive Grade Temp. stability at -55 to +125°C, ±25ppm
- MIL-STD-883 shock and vibration compliant
- Durable QFN Plastic Compact Packaging
- Standby or Disable Tri-state function
- Low jitter (Period jitter RMS and Phase jitter RMS)

APPLICATIONS:

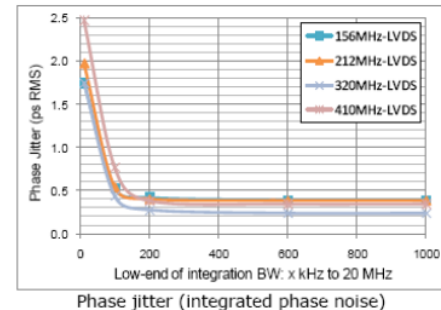
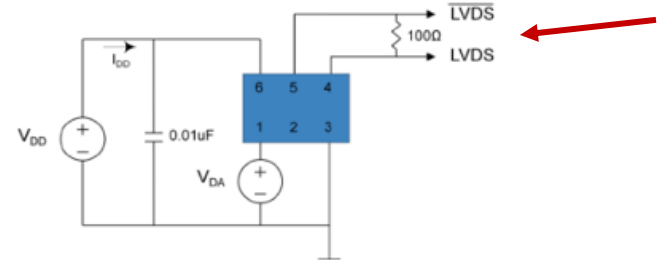
- Storage Area Networks (SATA, SAS, Fiber Channel)
- Passive Optical Networks (EPON, 10G-EPON, GPON, 10G-PON)
- Ethernet (1G, 10GBASE-T/KR/LR/SR, FCoE)
- PCI Express
- Display port

Common Key Electrical Specifications – CMOS, LVPECL, LVDS, and HCSL

Parameters	Minimum	Typical	Maximum	Units	Notes	
Frequency Range	CMOS	2.3000*		170.0000	MHz	-20 ~ +70°C
	CMOS	3.3000*		170.0000		-40 ~ +105°C
	LVPECL	2.3000*		460.0000		-55 ~ +125°C
	LVDS	2.3000*		460.0000		Commercial, Industrial temp. range
	HCSL	2.3000*		460.0000		Commercial, Industrial temp. range
Operating Temperature	-20		+70	°C	See options	
Storage Temperature	-55		+150	°C		
Overall Frequency Stability	-50		+50	ppm	See options	
Supply Voltage (V _{DD})	+2.25		+3.6	V		
Startup Time		5		ms		
Enable Time			20	ns	STD (Tri-state)	
Disable Time			5	ms	PD option (Power Down)	
			5	ns		
Disable Current			20	mA	STD (Tri-state)	
			0.095		PD option (Power Down)	
Tri-state Function (Standby/Disable)	"1" (VIH ≥ 0.75 * V _{DD}) or Open: Oscillation "0" (VIL < 0.25 * V _{DD}): Hi Z			V	40kΩ pull-up resistor embedded	
Aging	-5.0		+5.0	ppm	First year	

Key Electrical Specifications – LVDS

Parameters	Minimum	Typical	Maximum	Units	Notes
Supply Current (I _{DD})		29	32	mA	RL=100Ω
Output Offset Voltage (V _{OS})	1.125		1.4	V	RL=100Ω differential
Delta Offset Voltage (ΔV _{OS})			50	mV	
Peak to Peak Output Swing (V _{pp})		350		mV	Single ended
Rise Time		200		ps	RL=50Ω, CL=2pF 20% to 80%
Fall Time		200			
Duty Cycle	48		52	%	Differential
Integrated Phase Jitter (J _{PHI})		0.28	2	ps	200kHz ~ 20MHz @156.25MHz 100kHz ~ 20MHz @156.25MHz 12kHz ~ 20MHz @156.25MHz
		0.40	2		
		1.70	2		
Period Jitter RMS (J _{PER})		2.5		ps	



Phase jitter (integrated phase noise)



CDCLVD110A

SCAS841D – FEBRUARY 2007 – REVISED DECEMBER 2016

CDCLVD110A Programmable Low-Voltage 1:10 LVDS Clock Driver

1 Features

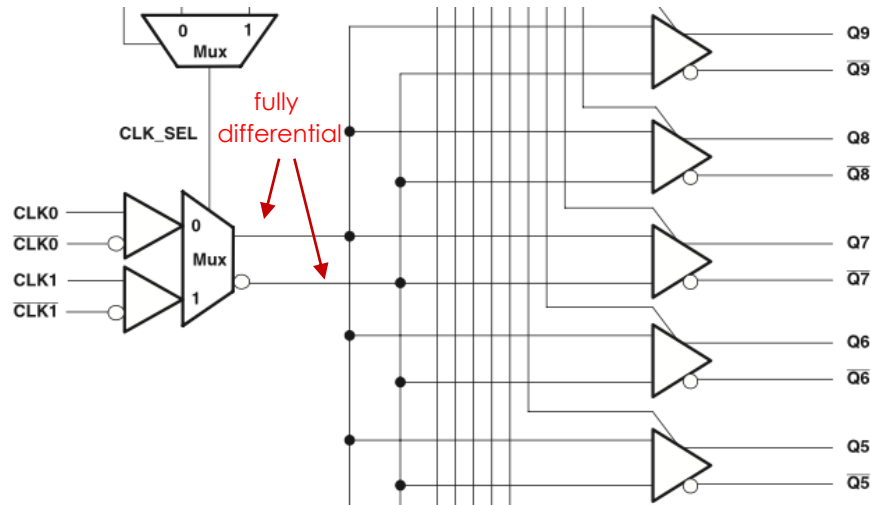
- Low-Output Skew <30 ps (Typical) for Clock-Distribution Applications
- Distributes One Differential Clock Input to 10 LVDS Differential Clock Outputs
- V_{CC} Range: 2.5 V \pm 5%
- Typical Signaling Rate Capability of Up to 1.1 GHz
- Configurable Register (SI/CK) Individually Enables/Disables Outputs, Selectable CLK0, CLK0 or CLK1, CLK1 Inputs
- Full Rail-to-Rail Common-Mode Input Range
- Receiver Input Threshold: \pm 100 mV
- Available in 32-Pin LQFP and VQFN Package
- Fail-Safe I/O-Pins for $V_{DD} = 0$ V (Power Down)

3 Description

The CDCLVD110A clock driver distributes one pair of differential LVDS clock inputs (either CLK0 or CLK1) to 10 pairs of differential clock outputs (Q0 to Q9) with minimum skew for clock distribution. The CDCLVD110A is specifically designed to drive 50- Ω transmission lines.

When the control enable is high (EN = 1), the 10 differential outputs are programmable in that each output can be individually enabled or disabled (3-stated) according to the first 10 bits loaded into the shift register. Once the shift register is loaded, the last bit selects either CLK0 or CLK1 as the clock input. However, when EN = 0, the outputs are not programmable and all outputs are enabled.

The CDCLVD110A has an improved start-up circuit that minimizes enabling time in AC- and DC-coupled systems.

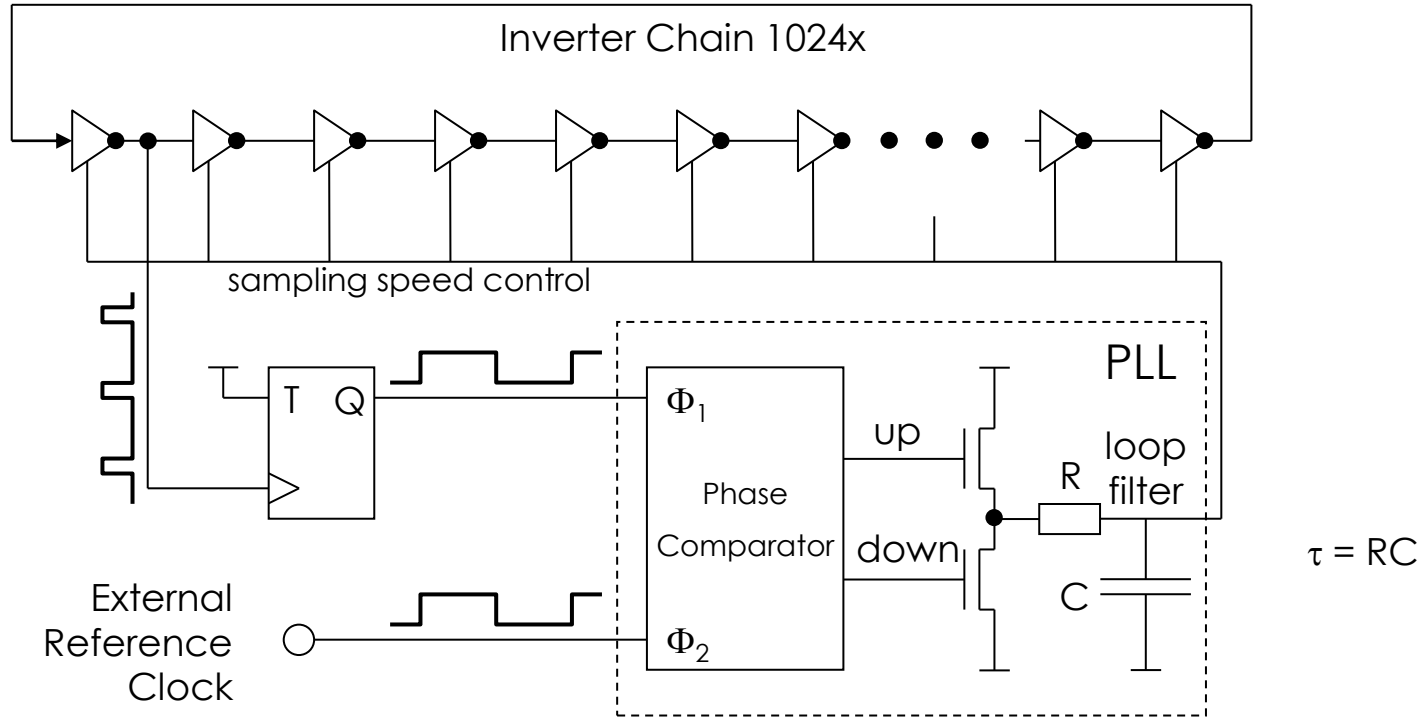


6.7 Jitter Characteristics

characterized with CDCLVD110 performance EVM, $V_{DD} = 3.3$ V, outputs not under test are terminated otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$t_{jitter, LVDS}$	Additive phase jitter from input to LVDS output Q3 and Q3		281		fs rms
		12 kHz to 20 MHz, $f_{out} = 125$ MHz	111		

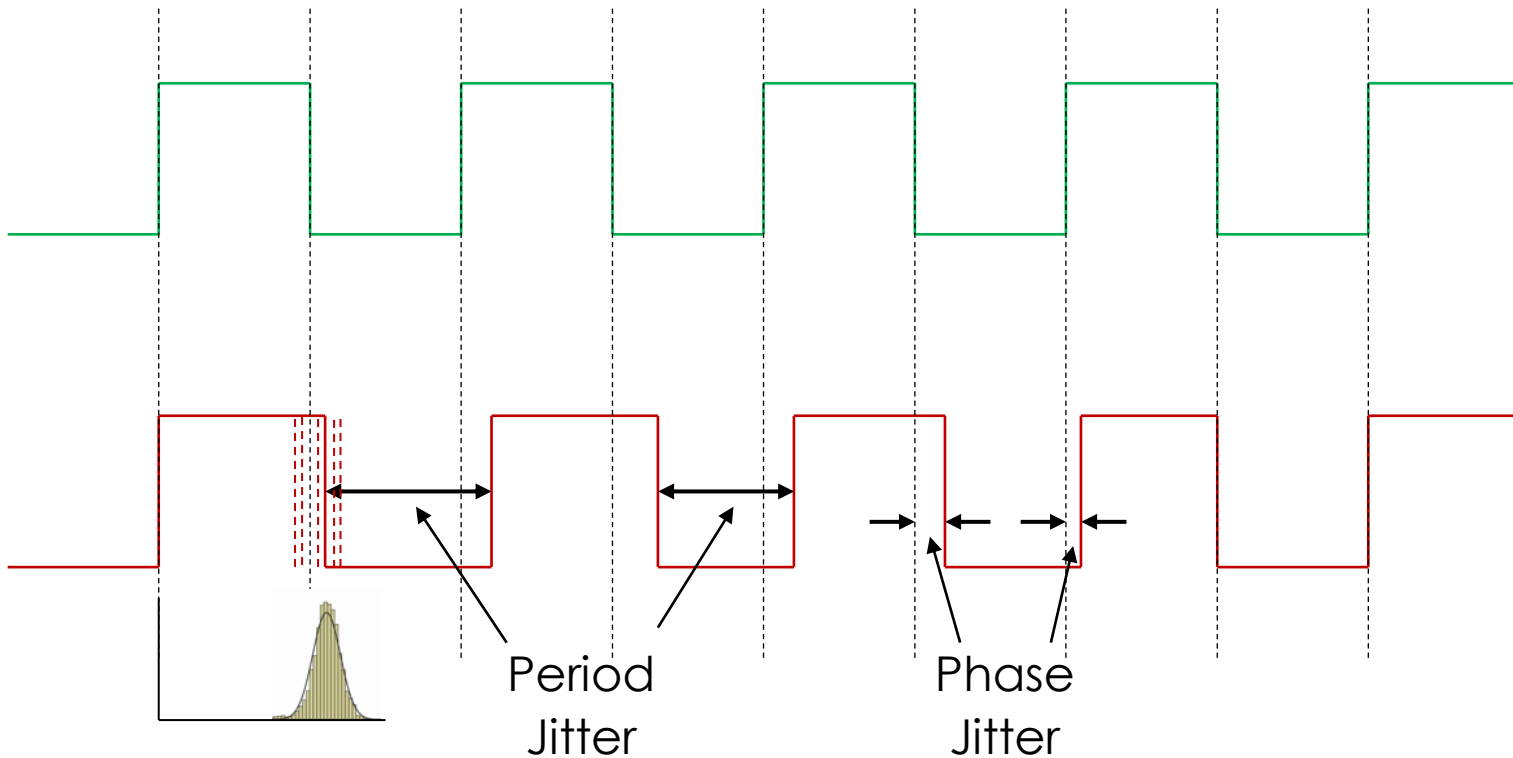
DRS4 Phase Locked Loop



PLL Jitter

Perfect
Clock

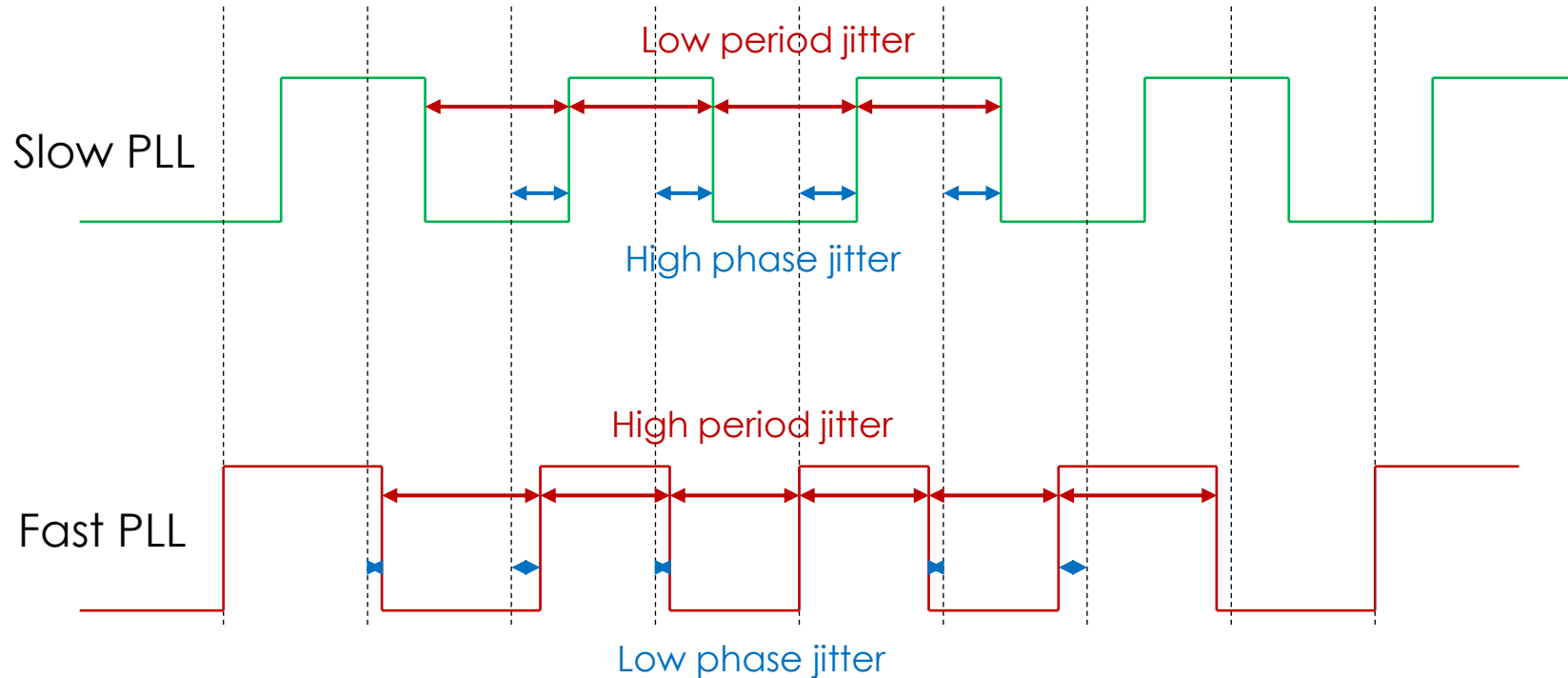
PLL
Clock



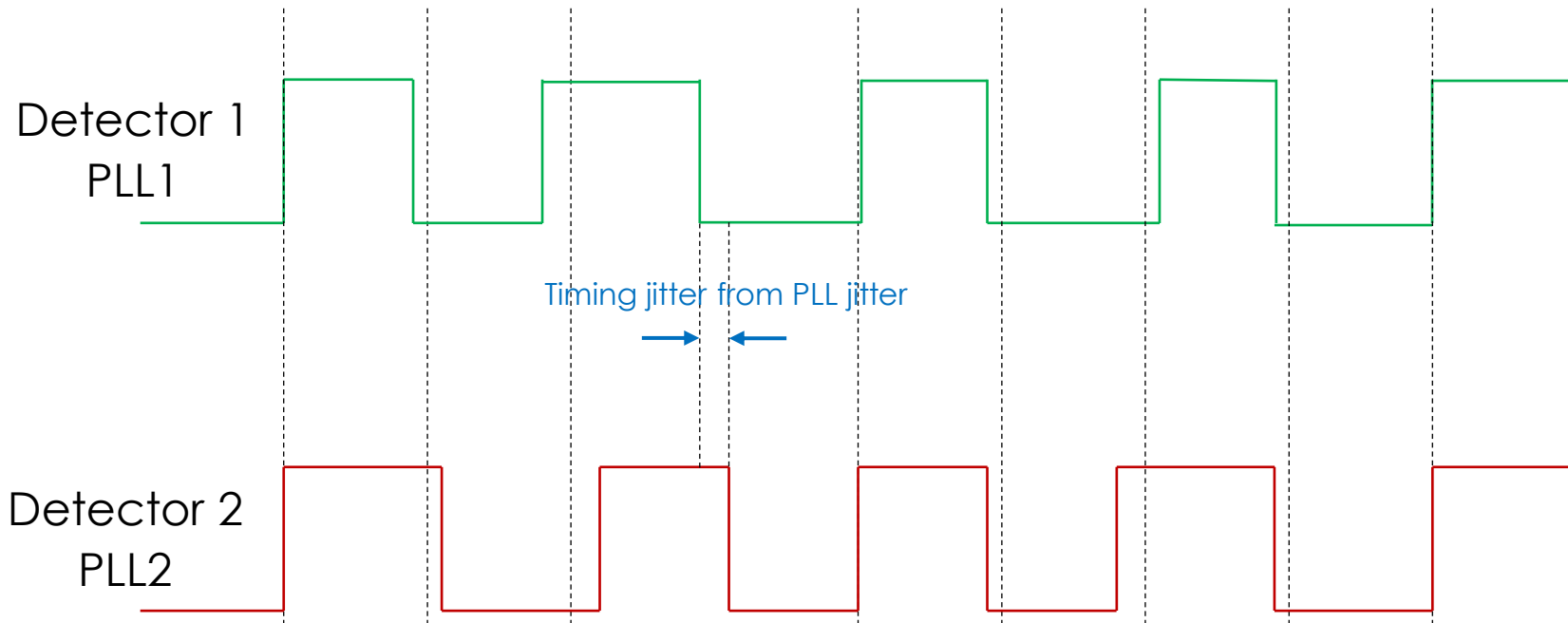
Period
Jitter

Phase
Jitter

PLL Jitter



Jitter between two PLLs

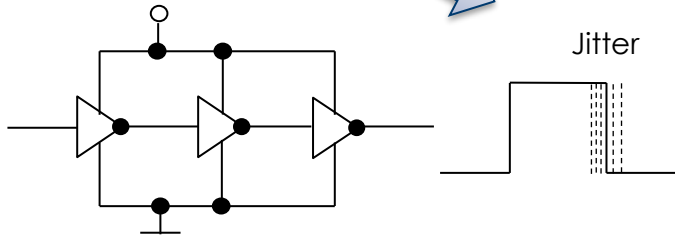


To achieve minimal timing jitter, PLL phase jitter must be minimized

PLL jitter from power supply noise

Power Noise

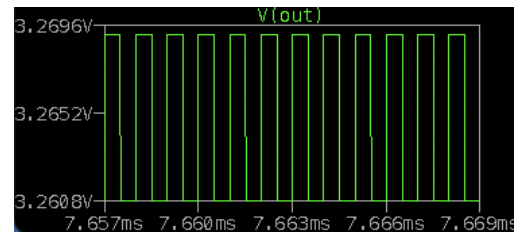
VDD



DRS4 chip: 1 mV noise → 10 ps jitter

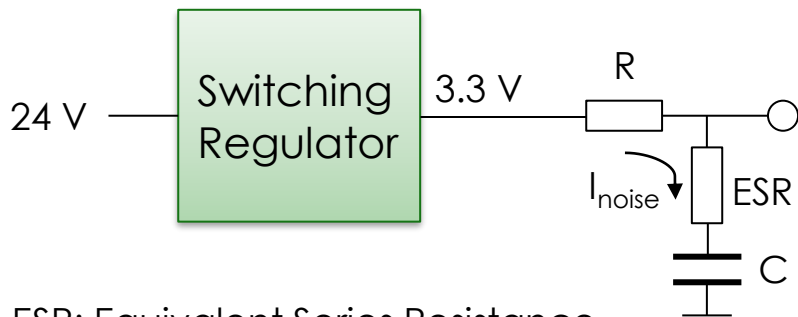
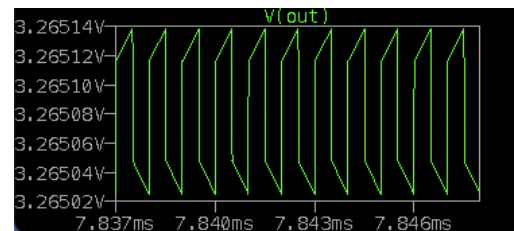
ESR = 1 Ohm

8 mV

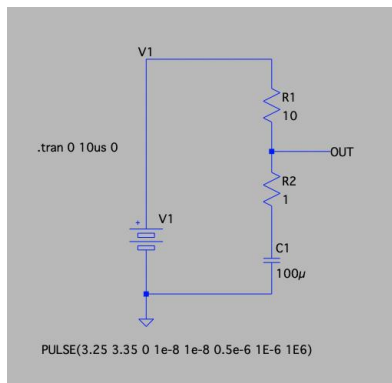


ESR = 0.01 Ohm

0.1 mV



ESR: Equivalent Series Resistance



Use low-ESR capacitors for power supply filtering

Used filter components

CONDUCTIVE POLYMER ALUMINUM SOLID ELECTROLYTIC CAPACITORS

nichicon

CK series

Chip Type, Ultra-low ESR



- Ultra-low ESR, Higher Capacitance, High ripple current.
- Load life of 2000 hours at 105°C.
- SMD type : Lead free reflow soldering condition at 260°C peak correspondence.
- Compliant to the RoHS directive (2002/95/EC).

CJ Low ESR → **CK**

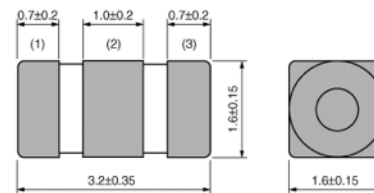


Standard Ratings

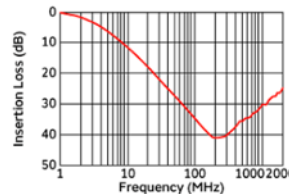
Rated Voltage (V)(code)	Surge Voltage (V)	Rated Capacitance (μF)	Case Size φD × L (mm)	tan δ	Leakage Current (μA)	ESR (mΩ) (at 100kHz 20°C)	Rated Ripple (mA Arms)	Part Number
2.5 (0E)	2.8	390	6.3 × 6	0.12	293	10	3900	PCK0E391MCO1GS
		560	8 × 7	0.12	420	9	4500	PCK0E561MCO1GS
		680	8 × 7	0.12	510	9	4500	PCK0E681MCO1GS
		1200	10 × 8	0.12	900	9	5000	PCK0E122MCO1GS
		2200	10 × 10	0.12	1650	8	6000	PCK0E222MCO1GS

↑
560 μF / 9 mΩ

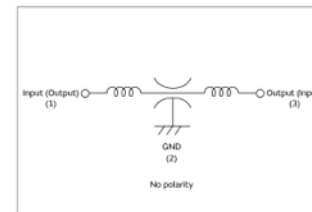
LC combines EMI Suppressor Filter NFE31PT222Z1E9



R = 100 mΩ

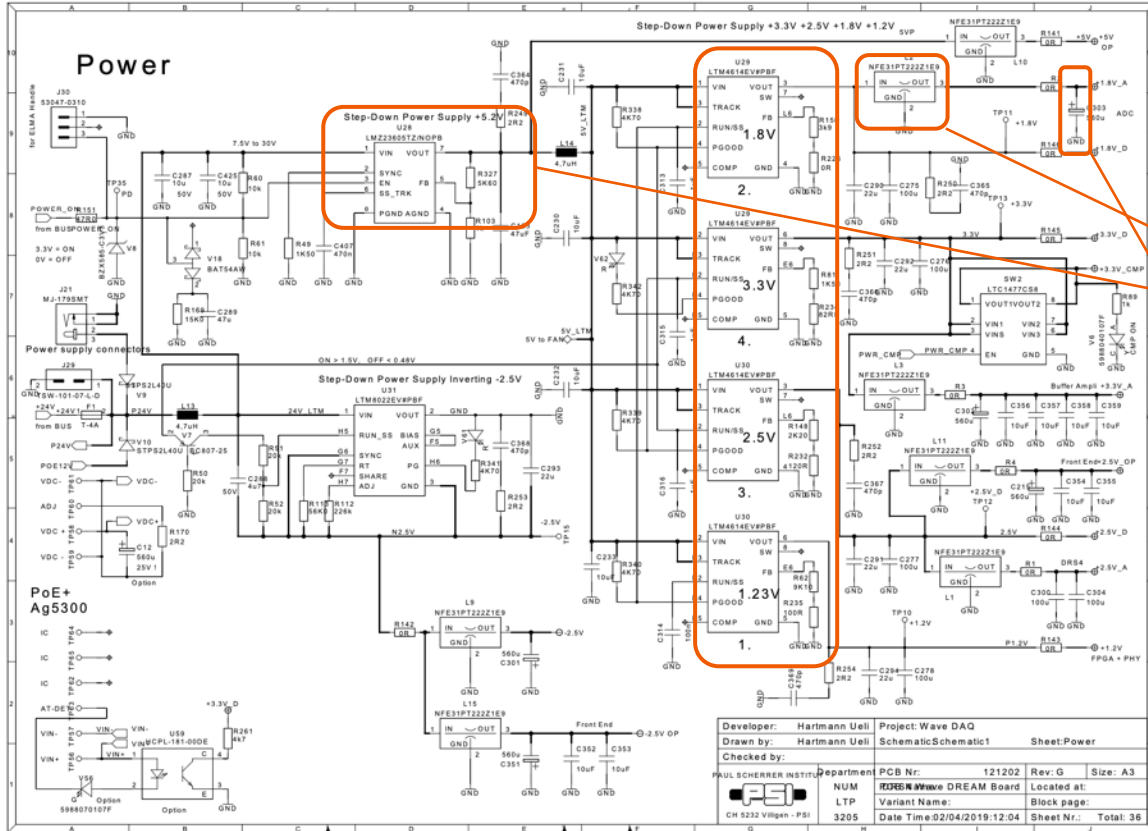


Insertion Loss Characteristics

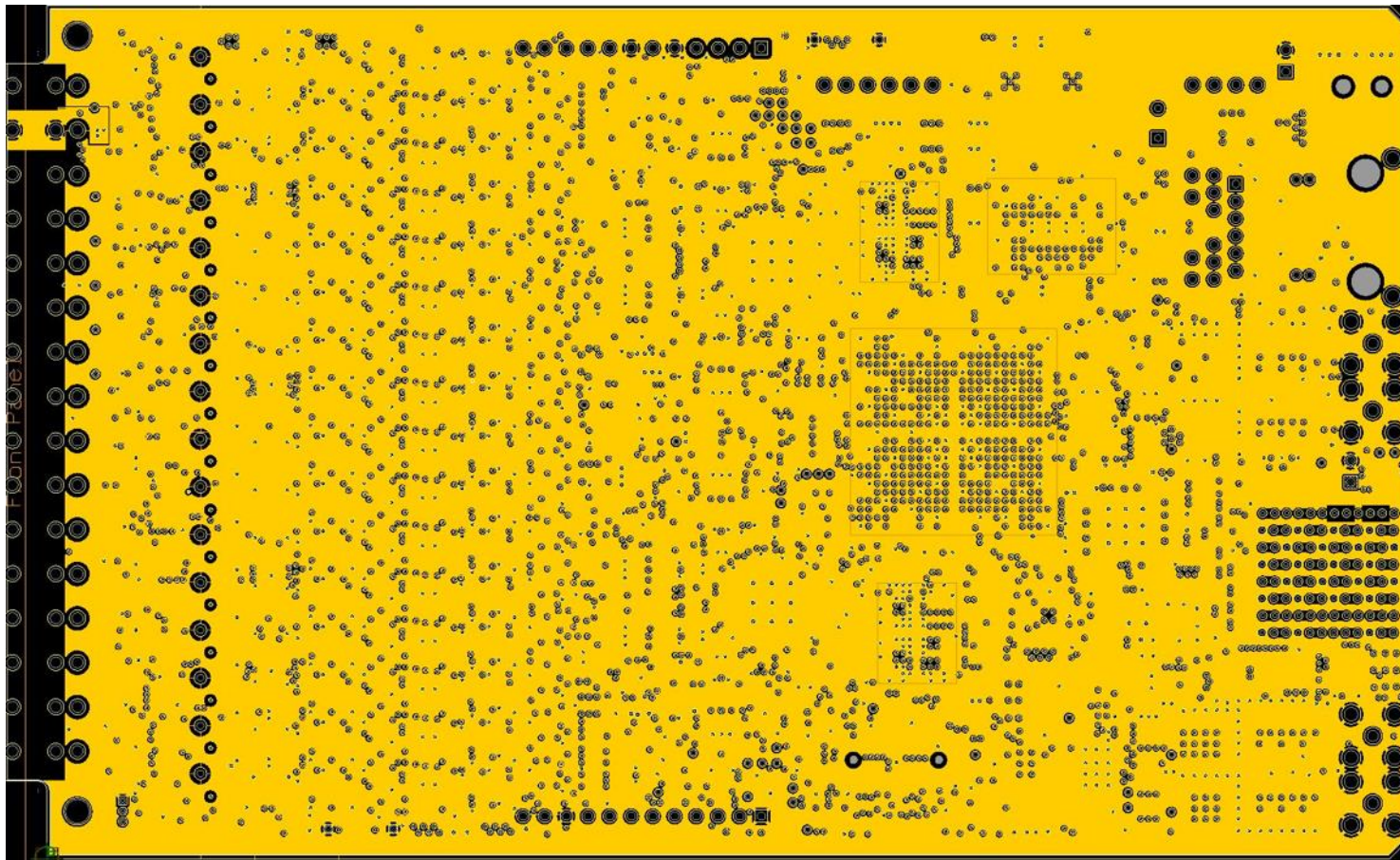


Equivalent Circuit

Power section WaveDREAM board

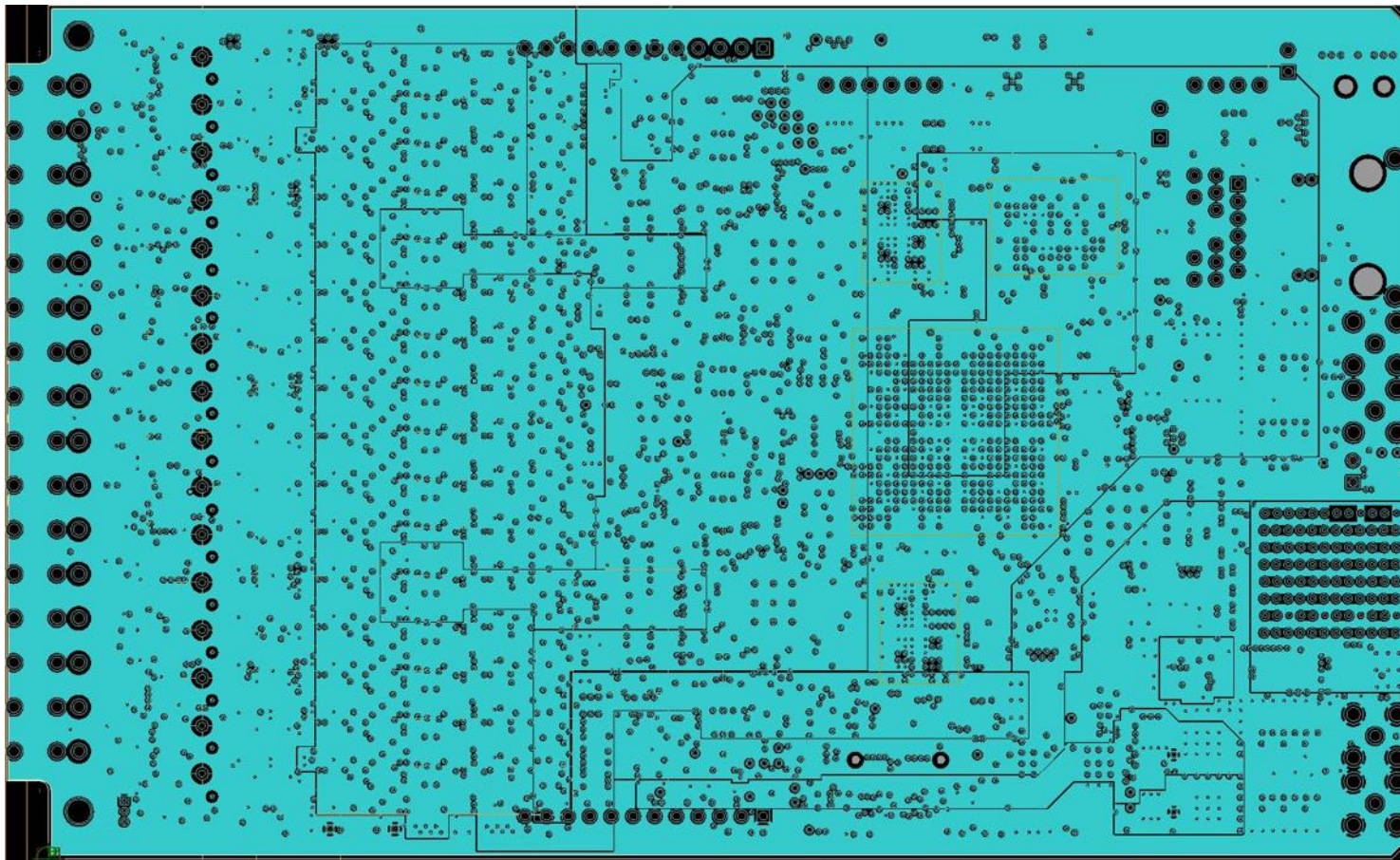


Ground Layer



F040001 Page 10

Power layer (1 out of 3)

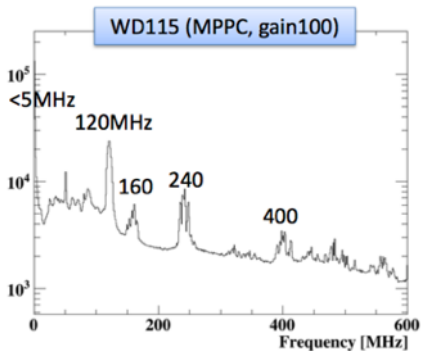
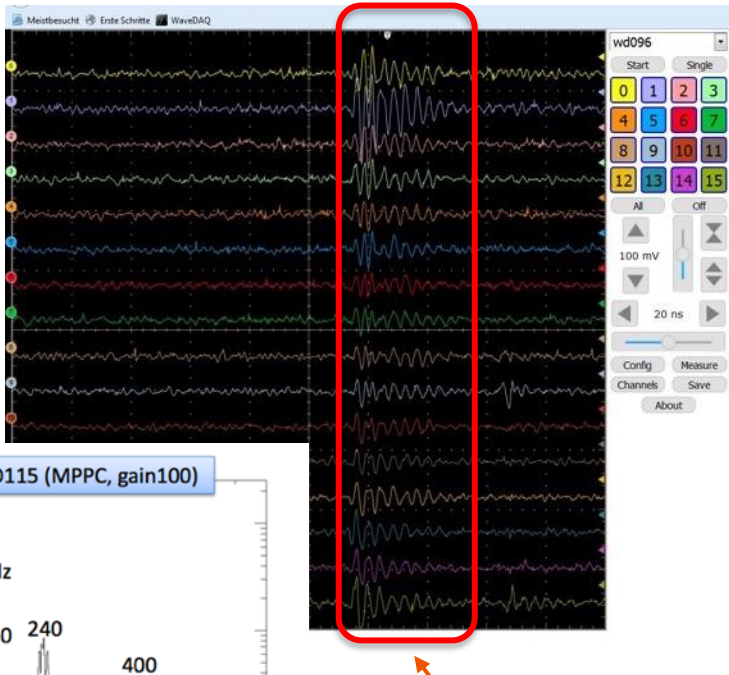
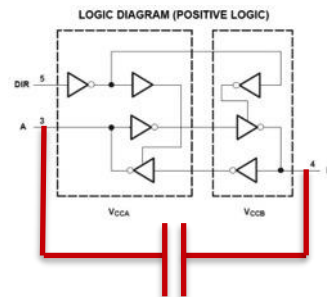


Electromagnetic Interference (EMI)

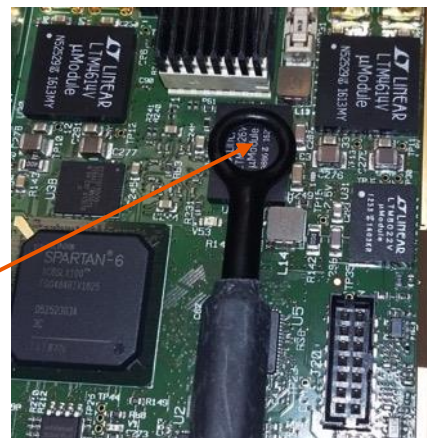
Shielding



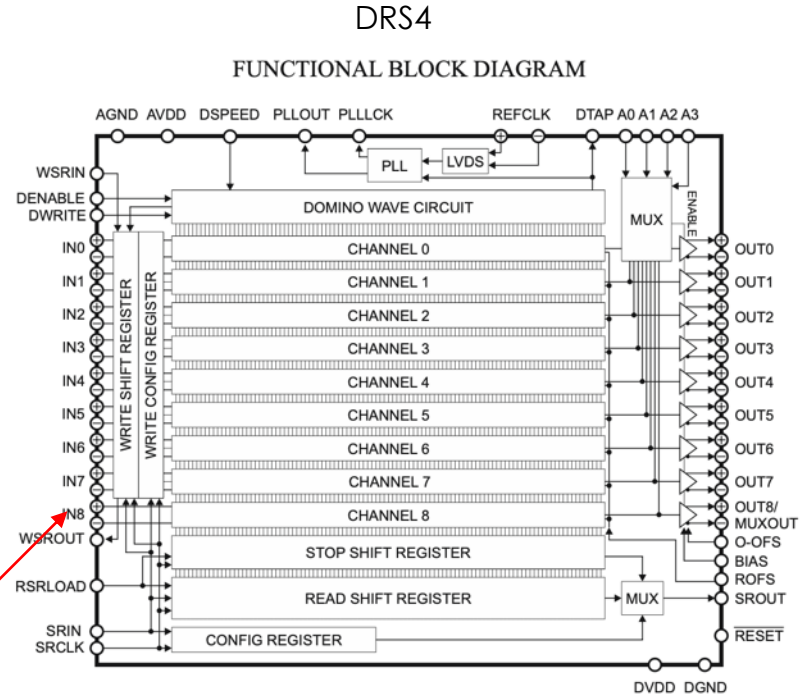
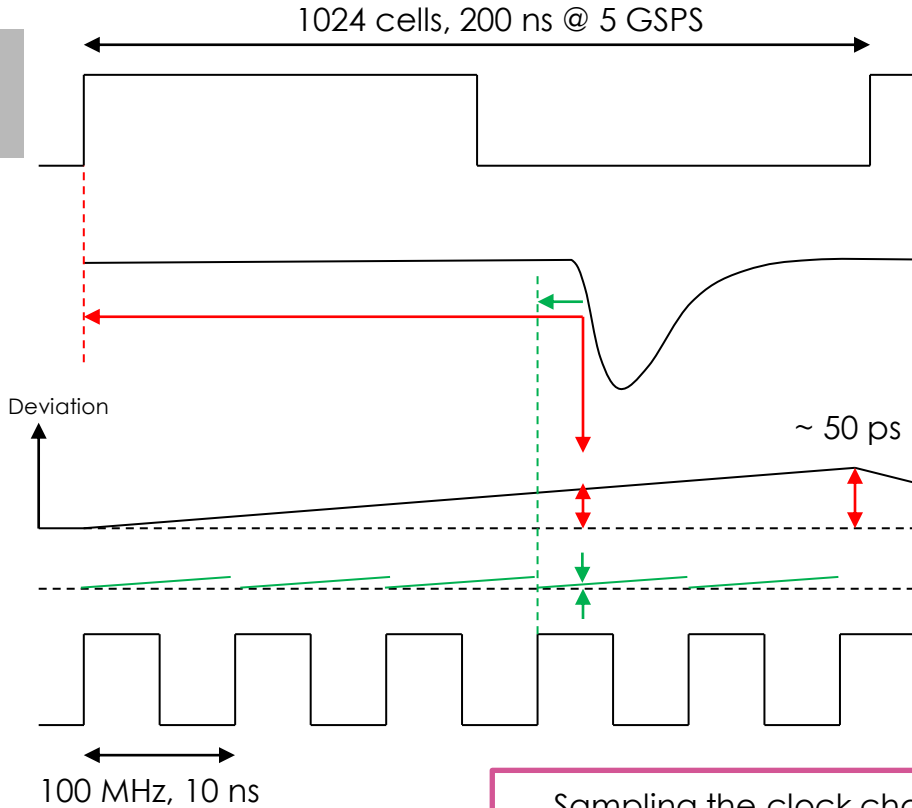
Slew rate limiter



EMI pulse from switching converter



Use of DRS4 clock channel



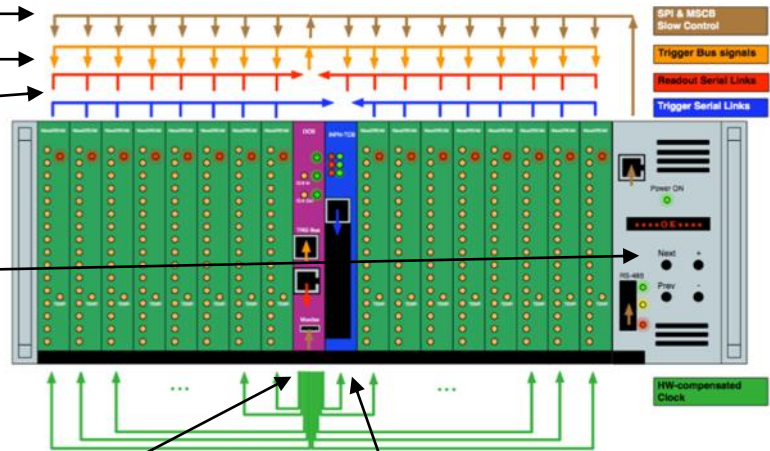
Sampling the clock channel reduces uncertainty from ~25 ps to <2 ps

The WaveDAQ system

Custom Design “WaveDAQ”



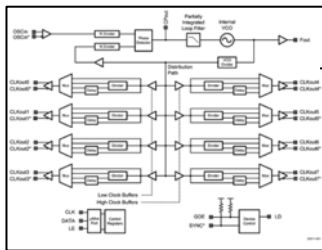
- Standard 19” crate + **custom backplane** (no VME, no xTCA)
- Idea: Not only a solution for MEG II, but **more general** “crate standard”
- Take the best ideas on the market and combine them
 - Serial bus (**SPI**) for configuration
 - **Trigger / Busy signals** in **backplane**
 - “**Dual Star**“ Serial gigabit links
 - **Hot-swap** functionality
 - Low jitter (<5 ps) clock
 - **Shelf management** with Ethernet interface
 - **24 V / 400 W** Power
 - fans control, temperature
 - Board management
 - **Firmware upload**



Data Concentrator Board (DCB)

Trigger Concentrator Board (TCB)

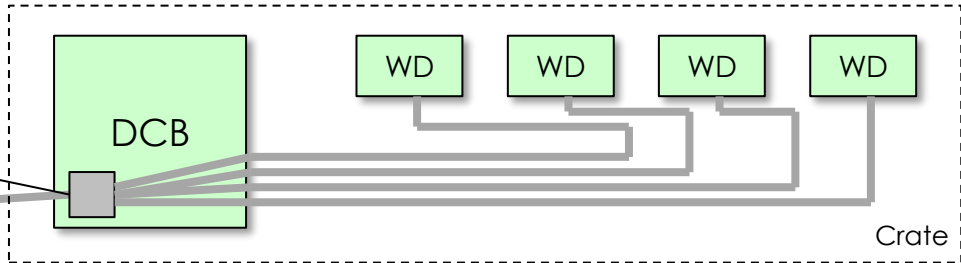
WaveDAQ Backplane



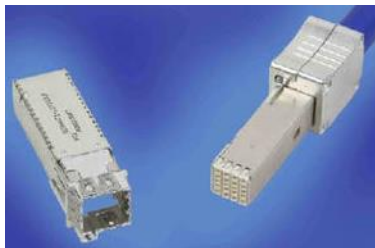
LMK03000 Jitter Cleaner



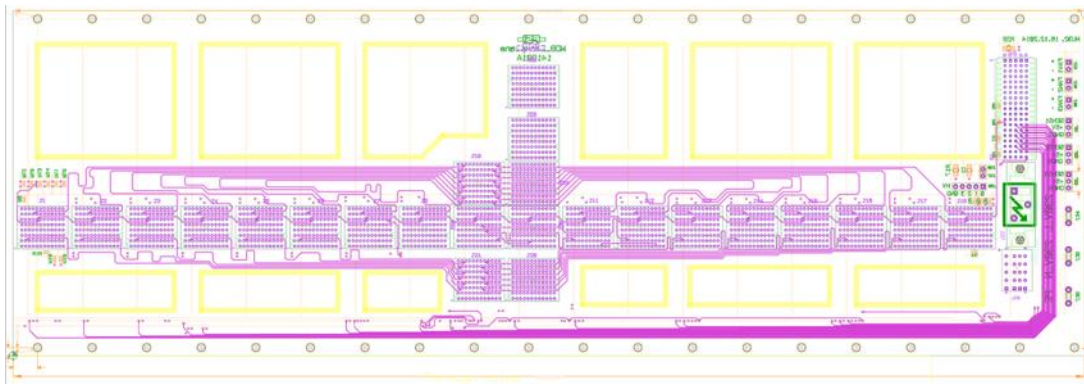
master
clock



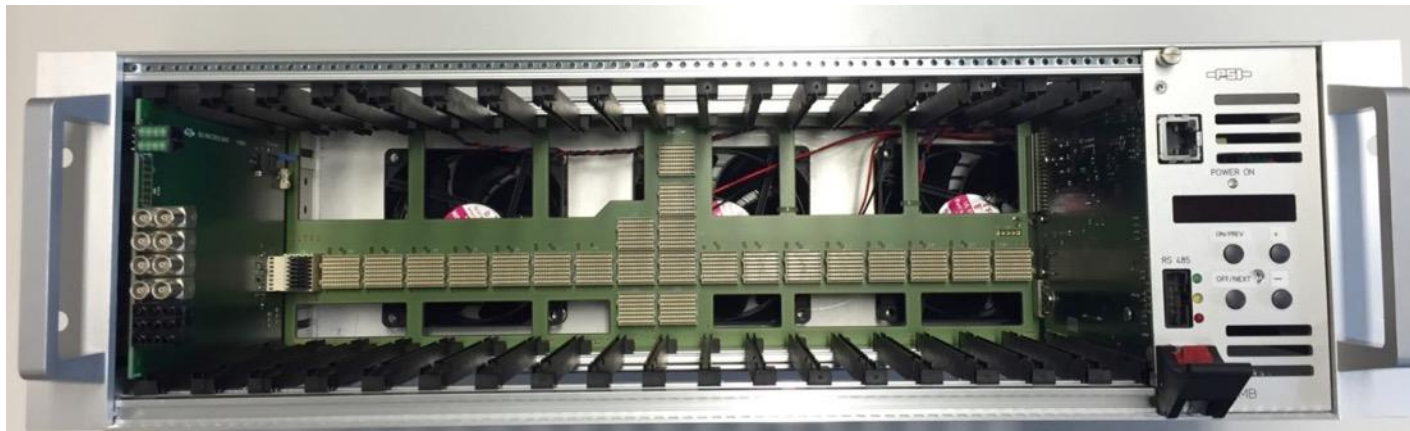
Crate



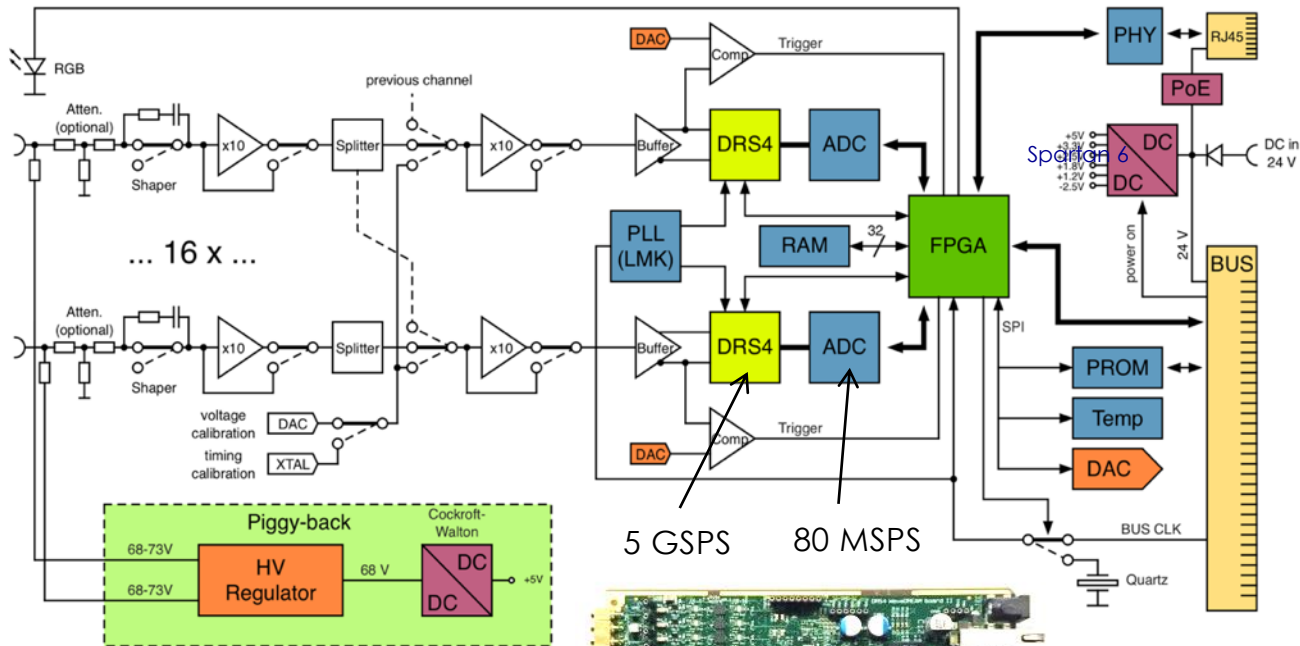
FCI Densishield Cable



Half Height Backplane



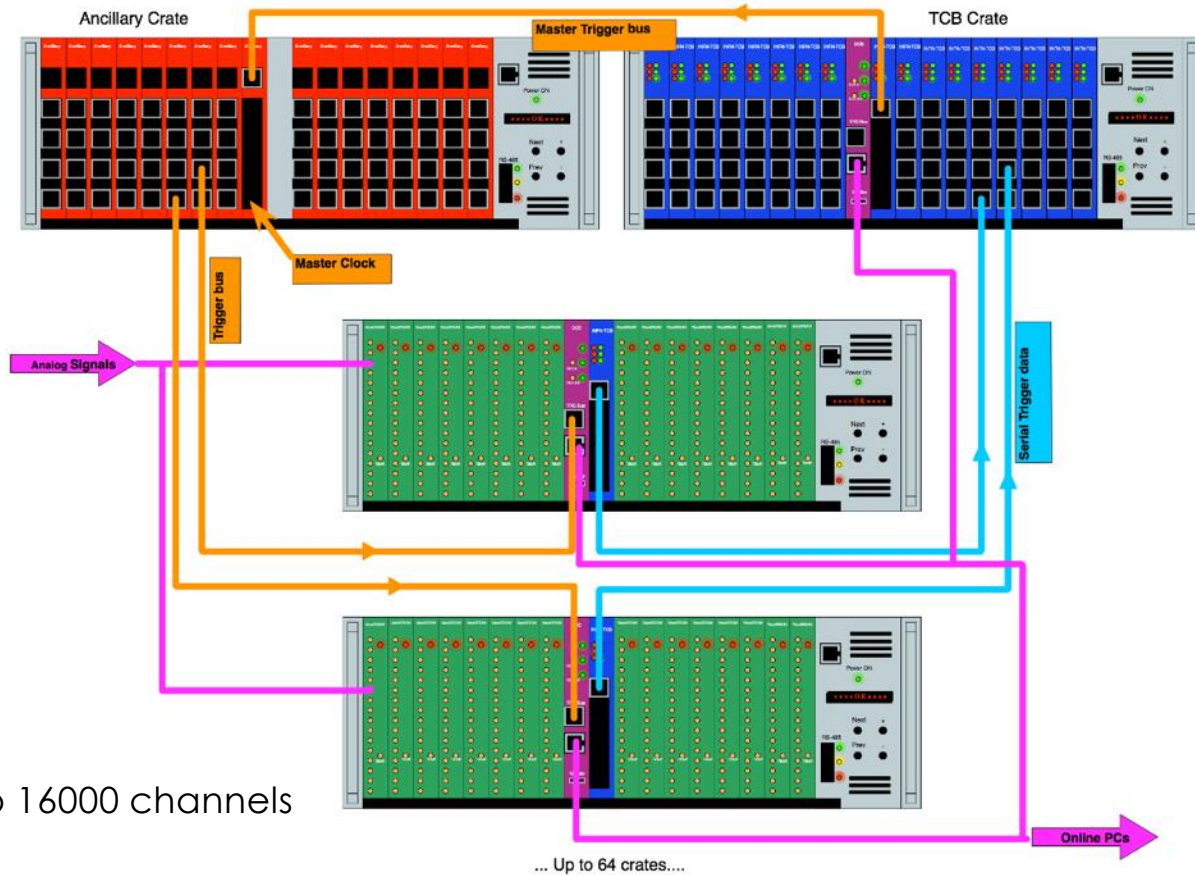
WaveDREAM Board (WDB)



Drs4 based REAdout Module



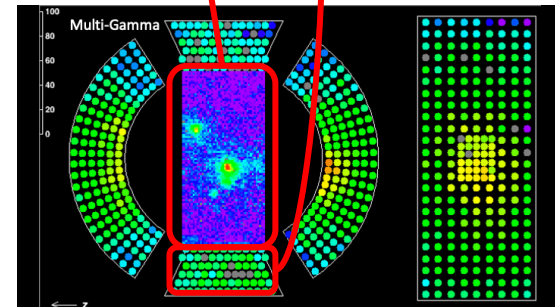
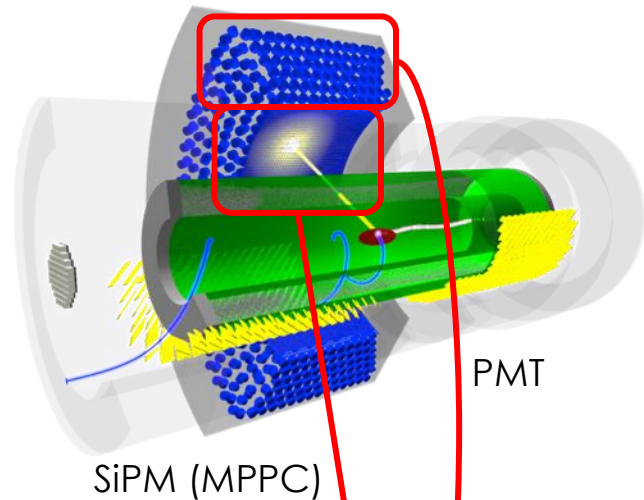
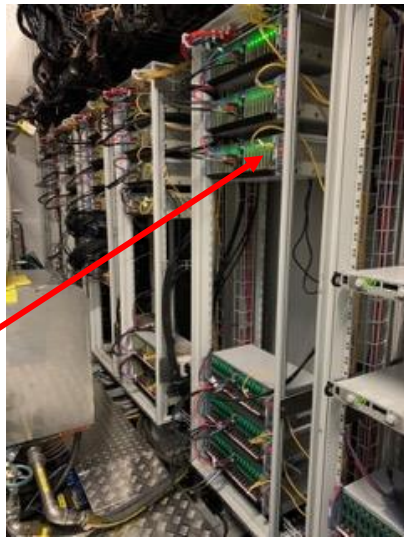
MEG II System



Scaling up to 16000 channels

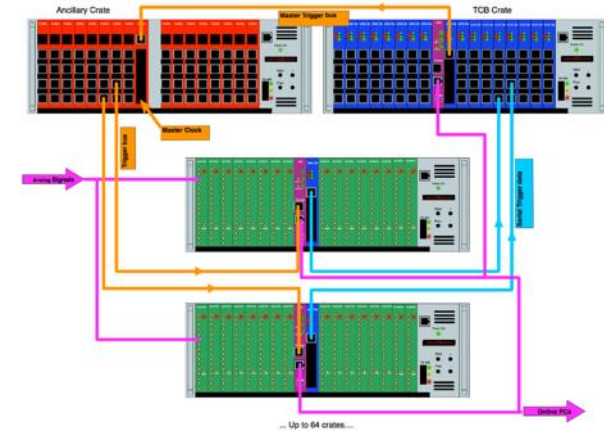
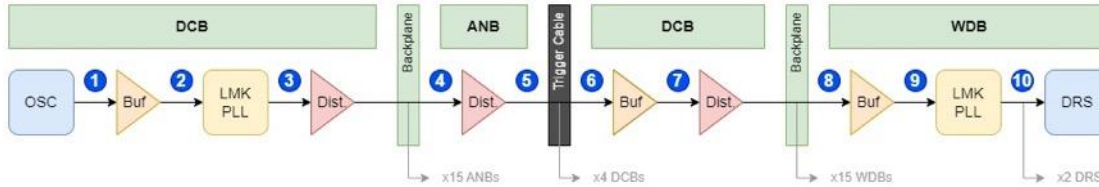
Liquid Xenon Detector

- **4092** channels SiPM & **668** channels PMT
(19 WaveDAQ crates)
- **Trigger** on calorimeter sum
- Greatly improved resolutions compared to MEG I



Jitter measurements

courtesy E. Schmidt, PSI



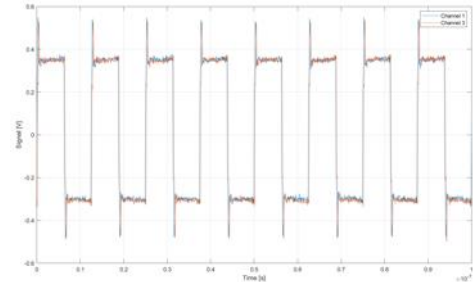
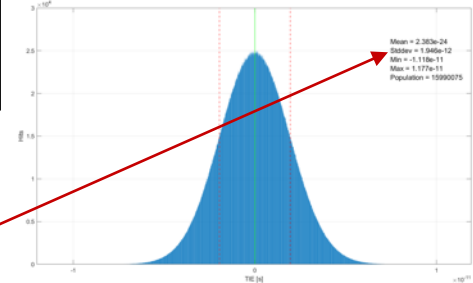
Filename + ToDo	Signal Probe Location	Signal	Ref Probe Location	Ref Signal	Jitter Std Dev	Jitter Min	Jitter Max
27_4_Crate190_AnbDistIn_vs_3_DcbDistIn Switch scope to refclk setup.	4	ANB Distributor Input (Soldered)	3	DCB Distributor Input (Soldered)	10.8 ps	-63.7 ps	53.2 ps
28_7_Crate196_DcbDistIn_vs_Crate192_DcbDistIn Solder 2 Probes to DCB02/DCB07 distributor input from Cable.	7	DCB Distributor Input (Soldered)	7	DCB Distributor Input (Soldered)	7.3 ps	-39.7 ps	45.5 ps
29_7_Crate196_DcbDistIn_vs_ScopeRef Switch to scope reference setup.	7	DCB Distributor Input (Soldered)	None	Scope Constant Clock	3.9 ps	-23.4 ps	31.0 ps
30_9_Crate196_Slot15WdbLmkin_vs_ScopeRef Solder 2 Probes to 2 WDB280/WDB317 LMK inputs.	9	WDB LMK Input (Soldered)	None	Scope Constant Clock	2.0 ps	-10.9 ps	12.3 ps
31_9_Crate196_Slot15WdbLmkin_vs_Slot1WdbLmkin Switch scope to refclk setup.	9	WDB LMK Input (Soldered)	9	WDB LMK Input (Soldered)	1.9 ps	-11.1 ps	11.8 ps
32_9_Crate196_Slot15WdbLmkin_vs_Crate192_Slot15WdbLmkin	9	WDB LMK Input (Soldered)	9	WDB LMK Input (Soldered)	3.0 ps	-16.4 ps	16.8 ps

Tektronix MSO64B
8 GHz, 50 GSPS
soldered diff. probes!

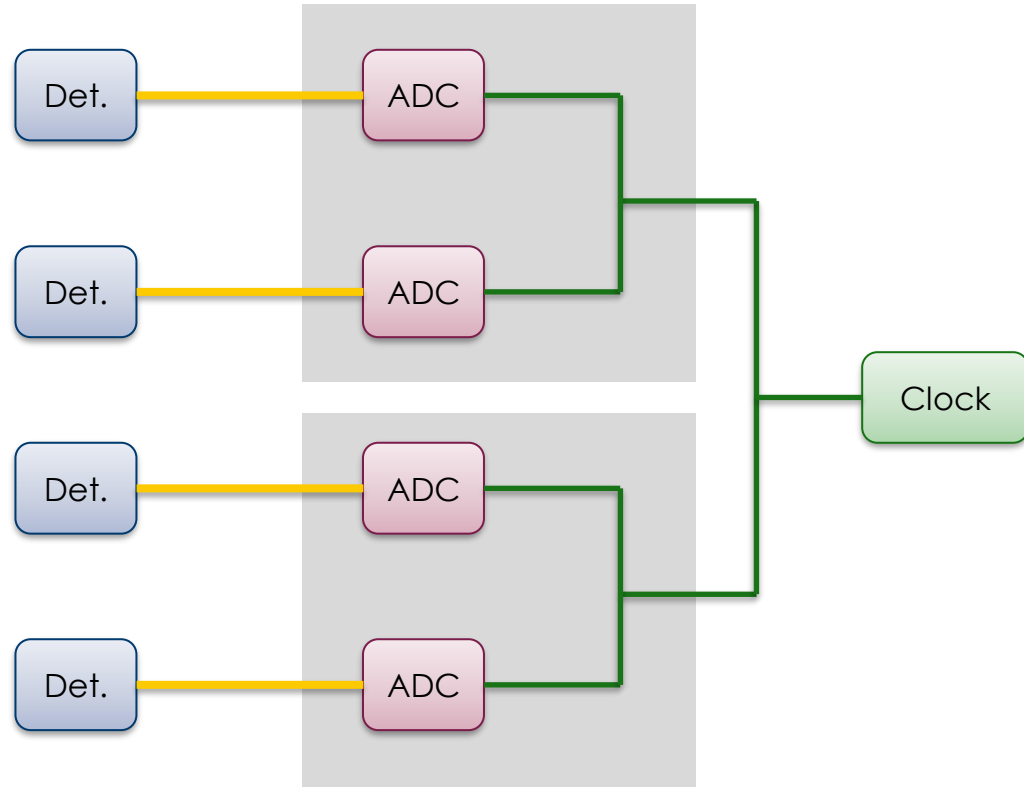
$\sigma_{\text{jitter}} = 1.9 \text{ ps}$

← Slot - Slot

← Crate - Crate

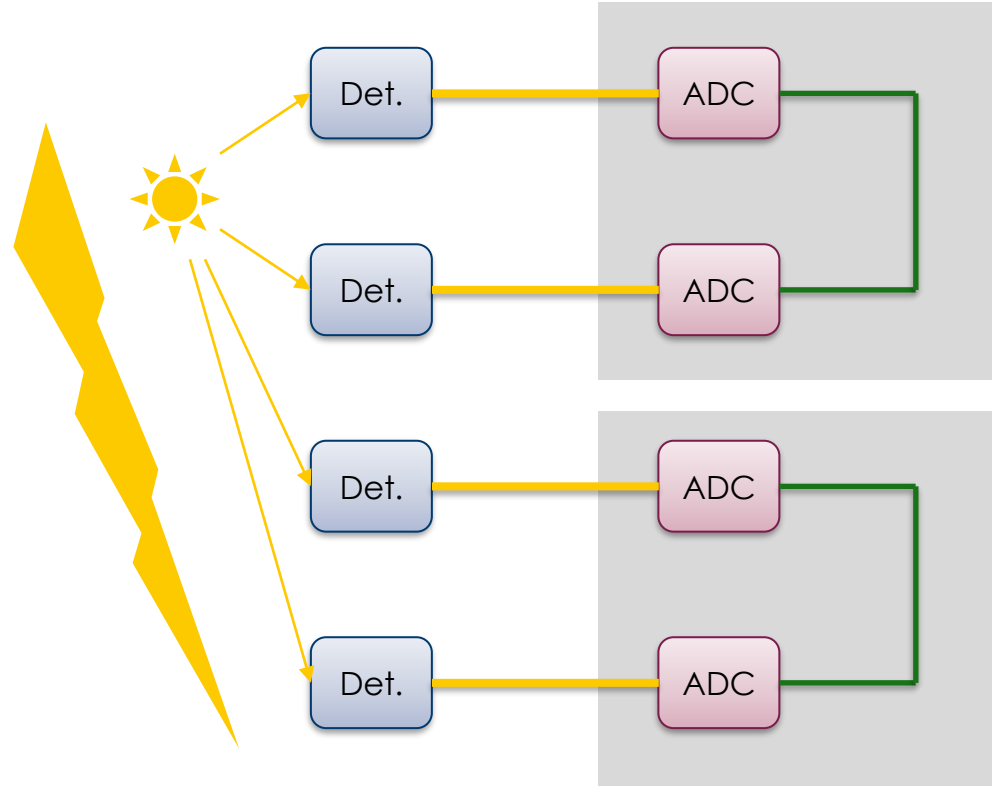


- Clock distribution is **never perfect** to the ps level
- Global sync injection at ADC does not calibrate **different cable lengths**
- Signal **injection** at detector can be **difficult**

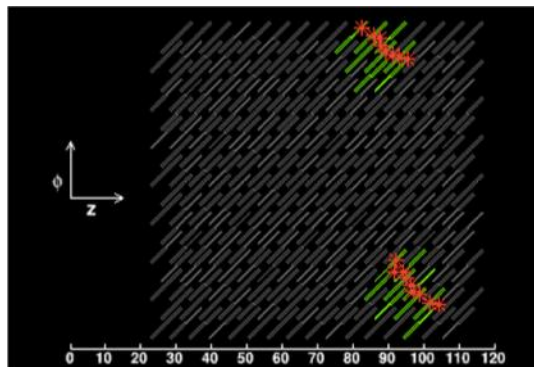
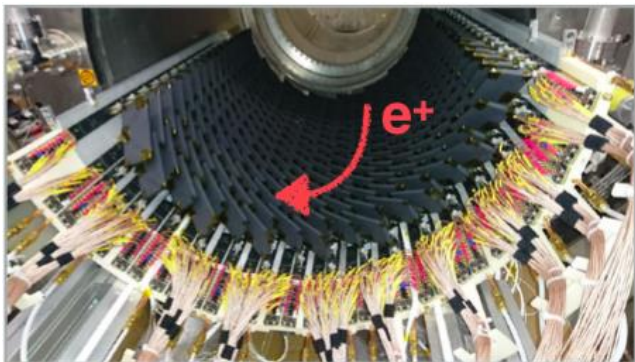


Solution: Use a **physics event** which is seen by all detectors:

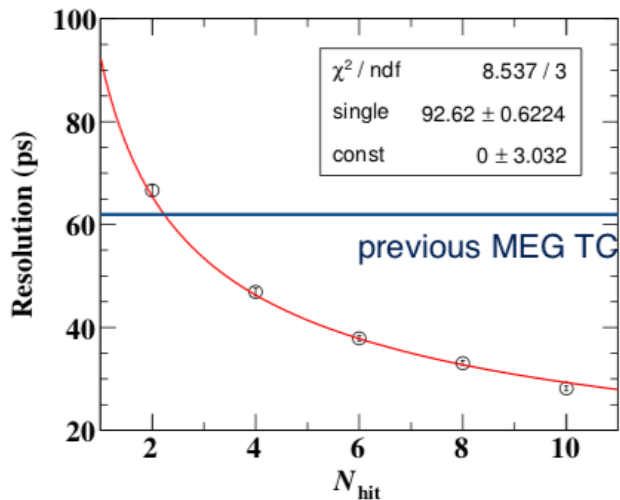
- **LED** flash in calorimeter
- **Cosmic** traversing many channels
- **Correct** for different light path



MEG II Timing Counter



- $8 \times 10^8 \mu/s$
- 256 scintillating tiles 4x6 cm,
512 WDB channels (2 crates)
- Resolution scales with \sqrt{N}
- **35 ps** reached with 8 hits



Lessons learned (so far...)

- Designing a **crate standard** is **easier** than anticipated (if no committee is involved 😊)
- Distributing a **5 ps** jitter clock is not very hard
- Doing everything from scratch can simplify things
 - **shelf manager** vs. 8-bit uC with few 100 lines of code
 - crate costs ~ **2k\$** including power supply
 - **1-wire** temperature sensor is great!
- Mixed signal board with **40 μV** of noise (gain=100 !) is **tough**
 - whole project took **6 years** from first idea with ~2 FTE
 - analog front-end took **1.5 years**, FW ~2 years
 - careful selecting and shielding
 - DC-DC** converter, needed **4 revisions**
 - the more noise you fix, the more new sources you find
 - Lots of **experience** obtained often missing in text books



Conclusions for precision timing in large systems

- Use end-to-end **differential** clock distribution
- Careful **filter** power for all PLLs with **low-ESR capacitors**
- Identify and remove **EMI sources**
- Large systems with **<5 ps** timing can be built
- I'm happy to **share** all my **experiences**

